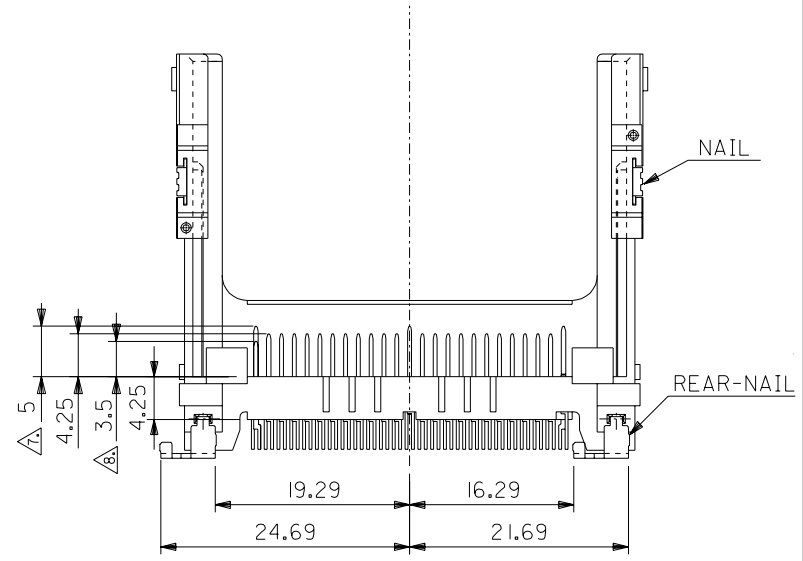
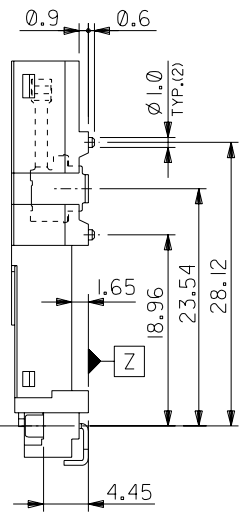
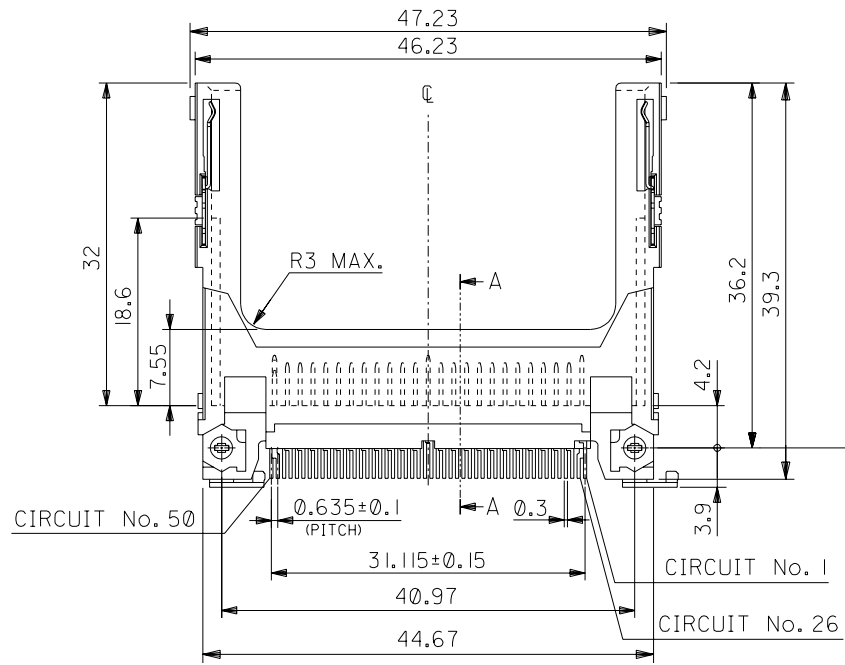
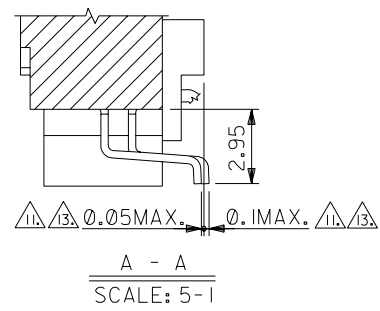
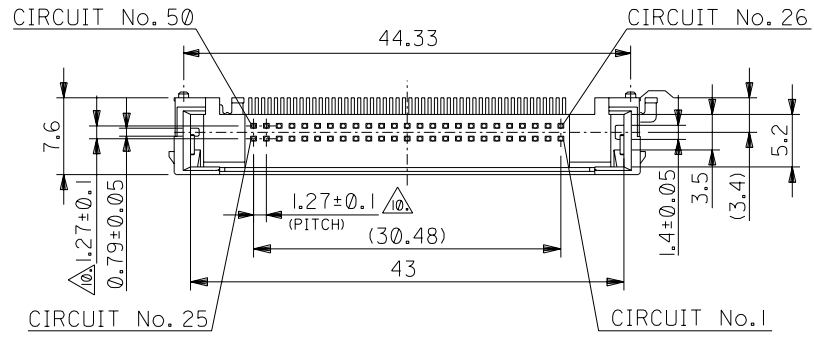


DWG. NO. SD-55358-014



DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:
RELEASED EC NO. J2004-3952 DRWN: M.NABEI '04/04/22 CHK: K.TOJO '04/04/22 APPR: M.SASAO '04/04/22			

DESCRIPTION	MATERIAL 材料	FINISH 仕上り	WIRE RANGE 適用線径範囲	INS. RANGE 被覆外径
	SEE NOTES	SEE NOTES	#	#

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 30 UNDER 以上 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

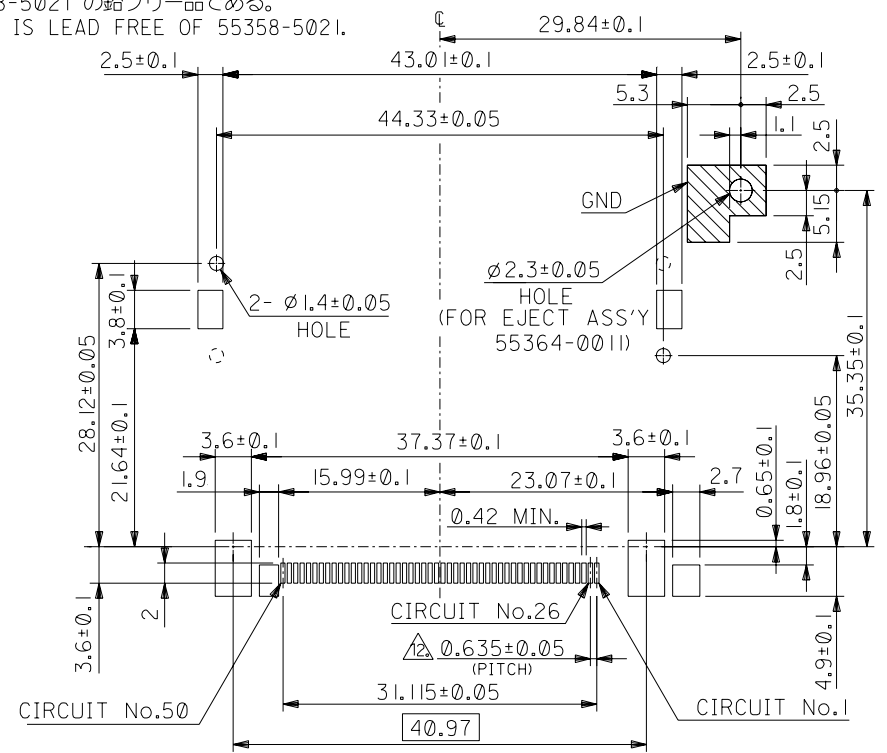
55358-5028		55358-5029		55358-50**	
HARD TRAY PACKAGE		MATERIAL No.		MODEL No.	
SCALE 2 - 1	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input type="checkbox"/> mm ONLY		SHT	REV
DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-			
CHECKED BY & DATE K.TOJO '04/04/22		MATERIAL NO. DRAWING NO. SHEET NO. SD-55358-014.S01 SEE CHART SD-55358-014 1 OF 2			
APPROVED BY & DATE M. Sasao '04/04/22		MATERIAL NO. DRAWING NO. SHEET NO. SD-55358-014.S01 SEE CHART SD-55358-014 1 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					
					SIZE B

DWG. NO. SD-55358-014

DO NOT SCALE DRAWING

- 8 7 6 5 4 3 2 1
- 注) NOTES
1. 材質 MATERIAL
 ハウジング: ガラス入りLCP UL94V-0
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
 ピン: リン青銅
 PIN: PHOSPHOR BRONZE
 ネール: リン青銅 (t0.3)
 NAIL: PHOSPHOR BRONZE (t0.3)
 リヤネール: リン青銅 (t0.48)
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING
 ピン PIN 接点部: パラジウムニッケル下地、金メッキ
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
 ネール NAIL 接点部: 金メッキ
 CONTACT AREA: GOLD
 半田付け部: 錫メッキ
 SOLDER TAIL AREA: TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
 リヤネール REAR-NAIL 錫メッキ
 TIN
 下地メッキ: ニッケルメッキ
 UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚: t=0.8 MIN.
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
 RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒
 HOUSING COLOR: BLACK
7. 寸法適用極: 1,13,38,50
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
8. 寸法適用極: 25,26
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

11. ソルダーテールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダーテールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
12. 公差非累積
 NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5021 の鉛フリー品である。
 THIS PRODUCT IS LEAD FREE OF 55358-5021.



基板推奨寸法
 RECOMMENDED P.C.B. LAYOUT

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	DESCRIPTION	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	DESIGN UNITS	MODEL NO.	DIMENSIONS:		SHT	REV
							SEE NOTES	10 UNDER 未滿	±0.2	2 - 1	mm	INCH	THIRD ANGLE PROJECTION	mm	INCH
REV	REV	REV	REV	REV	REV	DESCRIPTION	FINISH 仕上げ	10 OVER 以上	30 UNDER 未滿	±0.25	DRAWN BY & DATE M.NABEI '04/04/22	TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-			
							SEE NOTES	30 OVER 以上	±0.3	CHECKED BY & DATE K.TOJO '04/04/22					
REV	REV	REV	REV	REV	REV	DESCRIPTION	WIRE RANGE 適用電線範囲	—		±3°	APPROVED BY & DATE H. Sato '04/04/22	MOLEX INCORPORATED			
							ANGLE 角度	—		±3°	CAD FILENAME SD-55358-014.S02				
							INS. RANGE 被覆外径	—		±3°	MATERIAL NO.	DRAWING NO.	SHEET NO.	SIZE	
								—		±3°	—	SD-55358-014	2	B	

SD-55358-014.S02